



NUP1301

Ultra low capacitance ESD protection array

Rev. 01 — 11 May 2009

Product data sheet

1. Product profile

1.1 General description

Ultra low capacitance ElectroStatic Discharge (ESD) protection array in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package designed to protect one signal line in rail-to-rail configuration from the damage caused by ESD and other transients.

1.2 Features

- ESD protection of one signal line (rail-to-rail configuration)
- Ultra low diode capacitance: $C_d = 0.6$ pF
- Very low reverse leakage current: ≤ 30 nA
- ESD protection up to 30 kV
- IEC 61000-4-2; level 4 (ESD)
- IEC 61000-4-5 (surge); $I_{PP} = 11$ A at $t_p = 8/20$ μ s
- AEC-Q101 qualified

1.3 Applications

- Telecommunication networks
- Video line protection
- Microcontroller protection
- I²C-bus protection
- Antenna power supply
- Analog audio
- Class-D amplifier

1.4 Quick reference data

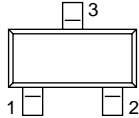
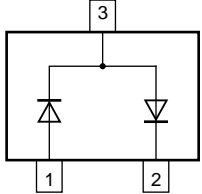
Table 1. Quick reference data

$T_{amb} = 25$ °C unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|------------------|---------------------------------|-----------------------------|-----|-----|------|------|
| Per diode | | | | | | |
| V_{RRM} | repetitive peak reverse voltage | | - | - | 80 | V |
| C_d | diode capacitance | $f = 1$ MHz; $V_R = 0$ V | - | 0.6 | 0.75 | pF |
| I_R | reverse current | $V_R = 80$ V | - | - | 100 | nA |

2. Pinning information

Table 2. Pinning

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|-----------------|----------------|--|---|
| 1 | GND | ground |  |  |
| 2 | V _{CC} | supply voltage | | |
| 3 | I/O | input/output | | |

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3. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|-------------|---------|--|---------|
| | Name | Description | Version |
| NUP1301 | - | plastic surface-mounted package; 3 leads | SOT23 |

4. Marking

Table 4. Marking

| Type number | Marking code ^[1] |
|-------------|-----------------------------|
| NUP1301 | LJ* |

- [1] * = -: made in Hong Kong
 * = p: made in Hong Kong
 * = t: made in Malaysia
 * = W: made in China

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|------------------|---------------------------------|---------------------------------|-----|-----|------|
| Per diode | | | | | |
| V _{RRM} | repetitive peak reverse voltage | | - | 80 | V |
| V _R | reverse voltage | | - | 80 | V |
| I _F | forward current | | [1] | 215 | mA |
| I _{FRM} | repetitive peak forward current | t _p ≤ 1 ms; δ ≤ 0.25 | - | 500 | mA |

Table 5. Limiting values ...continued

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-------------------|-------------------------------------|--|--------|------|------------------|
| I_{FSM} | non-repetitive peak forward current | square wave | [2] | | |
| | | $t_p = 1 \mu s$ | - | 4 | A |
| | | $t_p = 1 ms$ | - | 1 | A |
| | | $t_p = 1 s$ | - | 0.5 | A |
| Per device | | | | | |
| P_{PP} | peak pulse power | $t_p = 8/20 \mu s$ | [3][4] | - | 220 W |
| I_{PP} | peak pulse current | $t_p = 8/20 \mu s$ | [3][4] | - | 11 A |
| P_{tot} | total power dissipation | $T_{amb} \leq 25 \text{ }^\circ\text{C}$ | [5][6] | - | 250 mW |
| T_j | junction temperature | | - | 150 | $^\circ\text{C}$ |
| T_{amb} | ambient temperature | | -55 | +150 | $^\circ\text{C}$ |
| T_{stg} | storage temperature | | -65 | +150 | $^\circ\text{C}$ |

[1] Pulse test: $t_p \leq 300 \mu s$; $\delta \leq 0.02$.[2] $T_j = 25 \text{ }^\circ\text{C}$ prior to surge.[3] Non-repetitive current pulse 8/20 μs exponential decay waveform according to IEC 61000-4-5.

[4] Measured from pin 3 to pins 1 and 2 (pins 1 and 2 are connected).

[5] Single diode loaded.

[6] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

Table 6. ESD maximum ratings

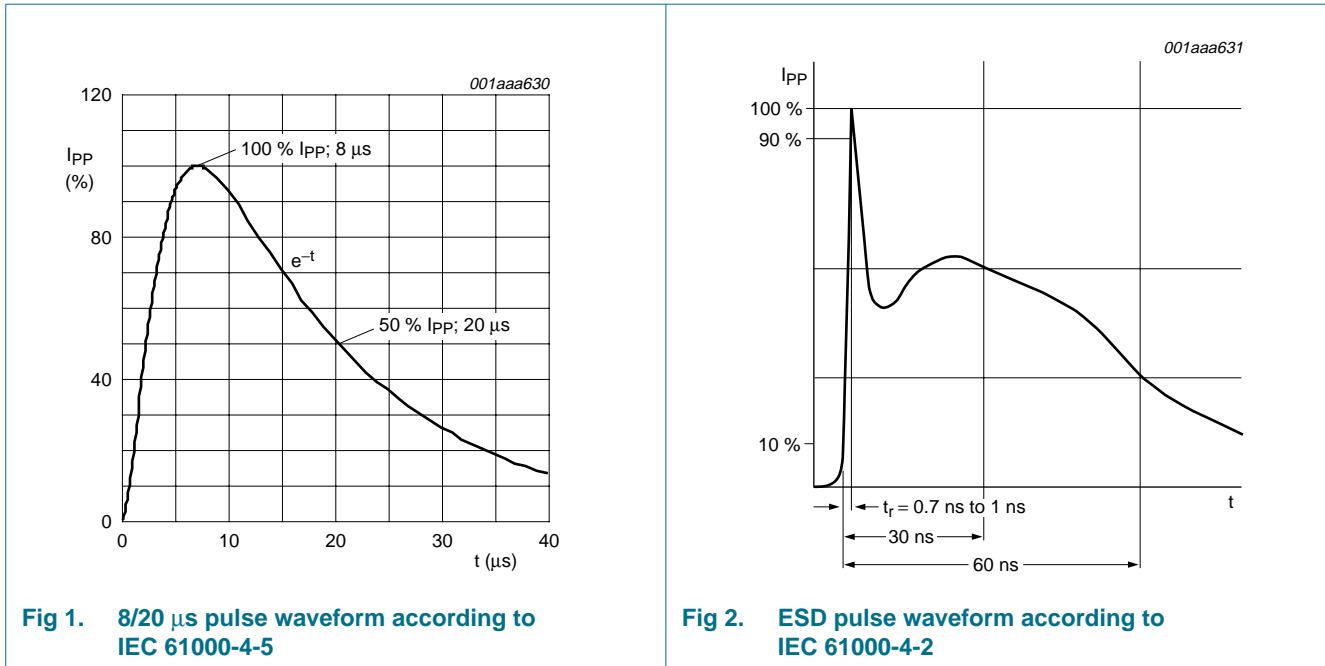
| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|---------------------------------|-----------------------------------|--------|-----|-------|
| V_{ESD} | electrostatic discharge voltage | IEC 61000-4-2 (contact discharge) | [1][2] | - | 30 kV |
| | | machine model | - | 400 | V |
| | | MIL-STD-883 (human body model) | - | 10 | kV |

[1] Device stressed with ten non-repetitive ESD pulses.

[2] Measured from pin 3 to pins 1 and 2 (pins 1 and 2 are connected).

Table 7. ESD standards compliance

| Standard | Conditions |
|--|---------------------------------|
| IEC 61000-4-2; level 4 (ESD) | > 15 kV (air); > 8 kV (contact) |
| MIL-STD-883; class 3B (human body model) | > 8 kV |



6. Thermal characteristics

Table 8. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------|--|-------------|--------|-----|-----|------|
| Per device | | | | | | |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | [1][2] | - | 500 | K/W |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point | | - | - | 360 | K/W |

[1] Single diode loaded.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

7. Characteristics

Table 9. Electrical characteristics

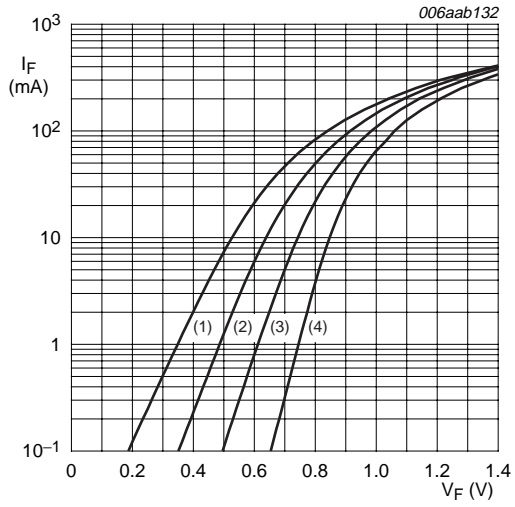
$T_{amb} = 25\text{ °C}$ unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------|-------------------|---|--------|-----|------|---------------|
| Per diode | | | | | | |
| V_{BR} | breakdown voltage | $I_R = 100\ \mu\text{A}$ | 100 | - | - | V |
| V_F | forward voltage | | [1] | | | |
| | | $I_F = 1\ \text{mA}$ | - | - | 715 | mV |
| | | $I_F = 10\ \text{mA}$ | - | - | 855 | mV |
| | | $I_F = 50\ \text{mA}$ | - | - | 1 | V |
| | | $I_F = 150\ \text{mA}$ | - | - | 1.25 | V |
| I_R | reverse current | | | | | |
| | | $V_R = 25\ \text{V}$ | - | - | 30 | nA |
| | | $V_R = 80\ \text{V}$ | - | - | 100 | nA |
| | | $V_R = 25\ \text{V};$ $T_j = 150\ \text{°C}$ | - | - | 25 | μA |
| | | $V_R = 80\ \text{V};$ $T_j = 150\ \text{°C}$ | - | - | 35 | μA |
| C_d | diode capacitance | $f = 1\ \text{MHz}; V_R = 0\ \text{V}$ | - | 0.6 | 0.75 | pF |
| Per device | | | | | | |
| V_{CL} | clamping voltage | $I_{PP} = 1\ \text{A}$ | [2][3] | - | 3 | V |
| | | $I_{PP} = 11\ \text{A}$ | [2][3] | - | 20 | V |

[1] Pulse test: $t_p \leq 300\ \mu\text{s}; \delta \leq 0.02$.

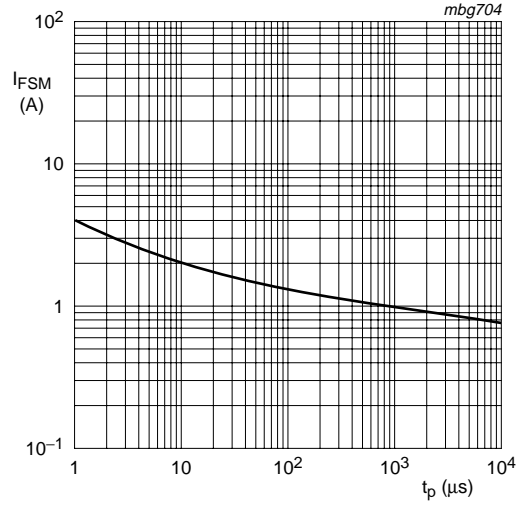
[2] Non-repetitive current pulse 8/20 μs exponential decay waveform according to IEC 61000-4-5.

[3] Measured from pin 3 to pins 1 and 2 (pins 1 and 2 are connected).



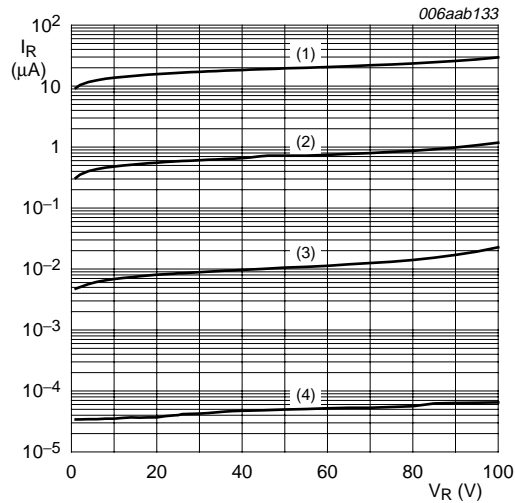
- (1) $T_{amb} = 150^\circ\text{C}$
- (2) $T_{amb} = 85^\circ\text{C}$
- (3) $T_{amb} = 25^\circ\text{C}$
- (4) $T_{amb} = -40^\circ\text{C}$

Fig 3. Forward current as a function of forward voltage; typical values



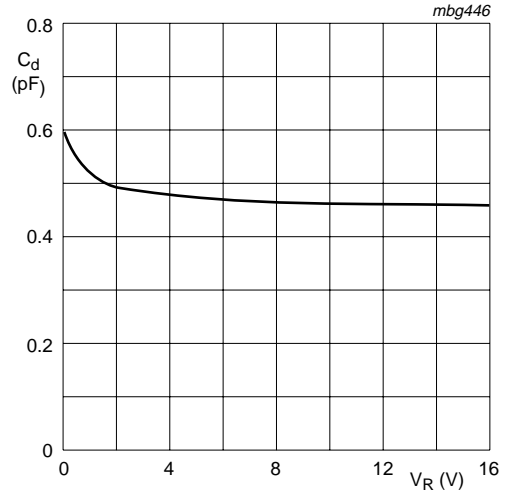
Based on square wave currents.
 $T_j = 25^\circ\text{C}$; prior to surge

Fig 4. Non-repetitive peak forward current as a function of pulse duration; typical values



- (1) $T_{amb} = 150^\circ\text{C}$
- (2) $T_{amb} = 85^\circ\text{C}$
- (3) $T_{amb} = 25^\circ\text{C}$
- (4) $T_{amb} = -40^\circ\text{C}$

Fig 5. Reverse current as a function of reverse voltage; typical values



$T_{amb} = 25^\circ\text{C}$; $f = 1\text{ MHz}$

Fig 6. Diode capacitance as a function of reverse voltage; typical values

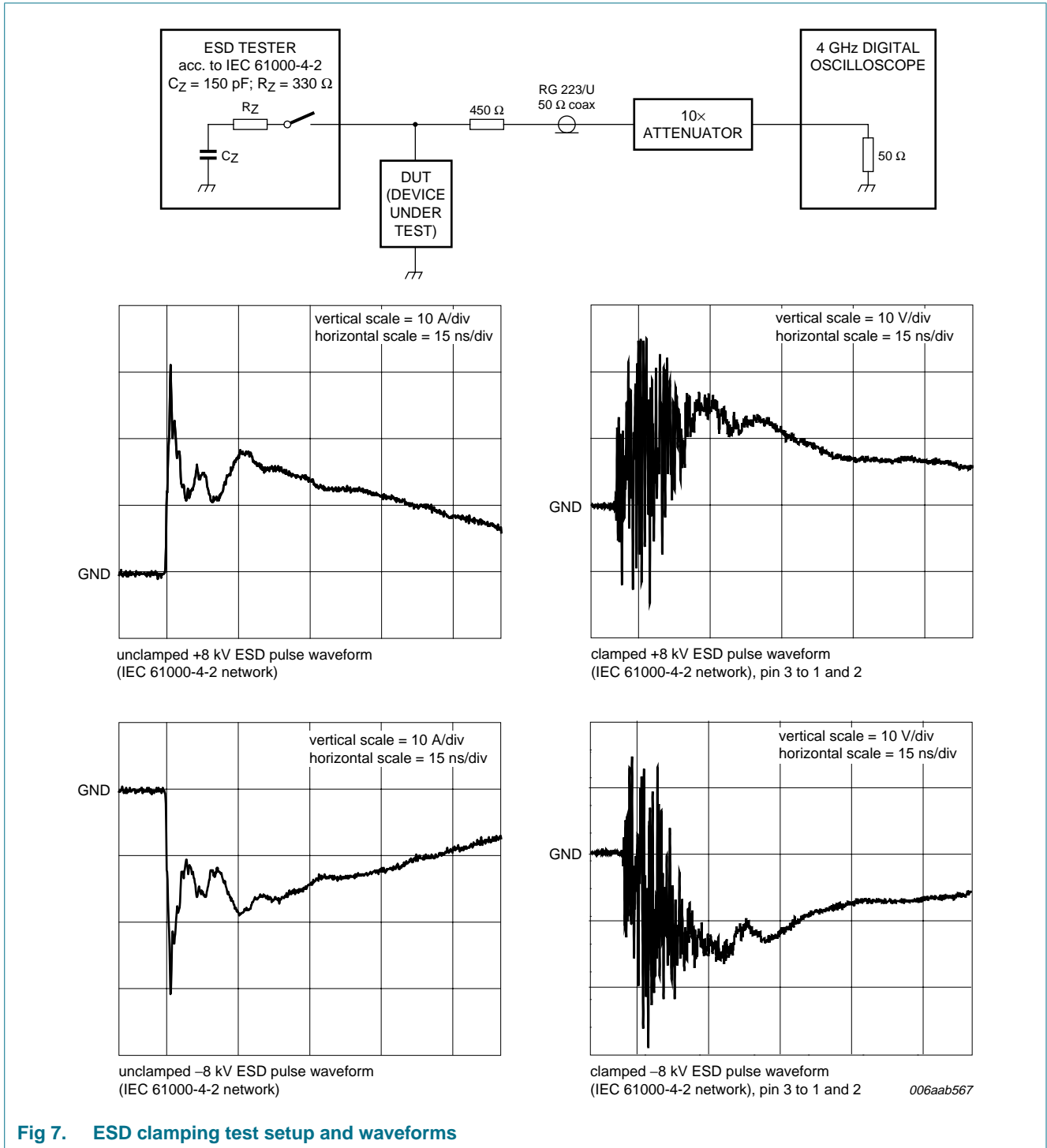


Fig 7. ESD clamping test setup and waveforms

8. Application information

Protection of a single (high-speed) data line in rail-to-rail configuration. The protected data line is connected to pin 3. Pin 1 is connected to ground (GND) and pin 2 is connected to the supply rail (supply voltage V_{CC} .) When the transient voltage exceeds the forward voltage drop of one diode, the transient is directed either to the supply rail or to GND. The advantages of these solutions are: low line capacitance (0.6 pF typically), fast response time, and low clamping voltage.

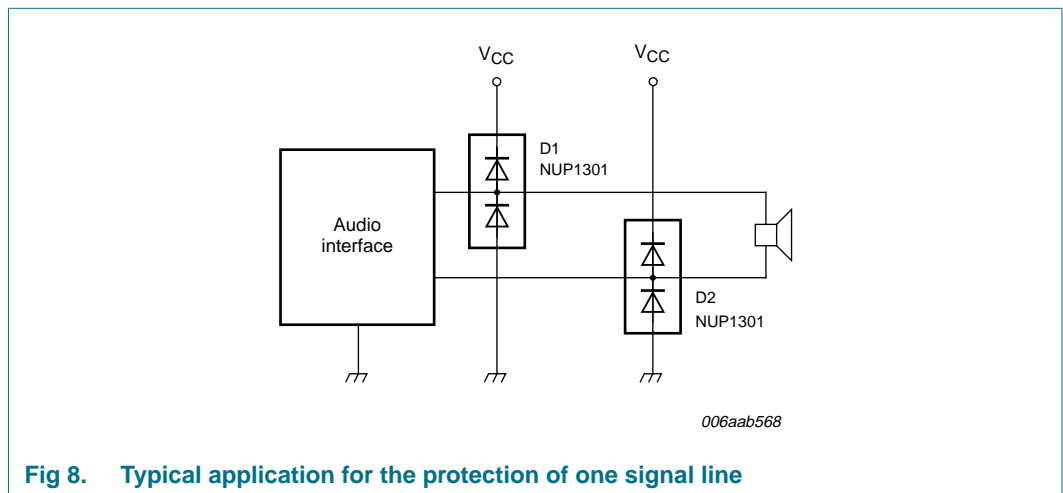


Fig 8. Typical application for the protection of one signal line

Circuit board layout and protection device placement:

Circuit board layout is critical for the suppression of ESD, Electrical Fast Transient (EFT) and surge transients. The following guidelines are recommended:

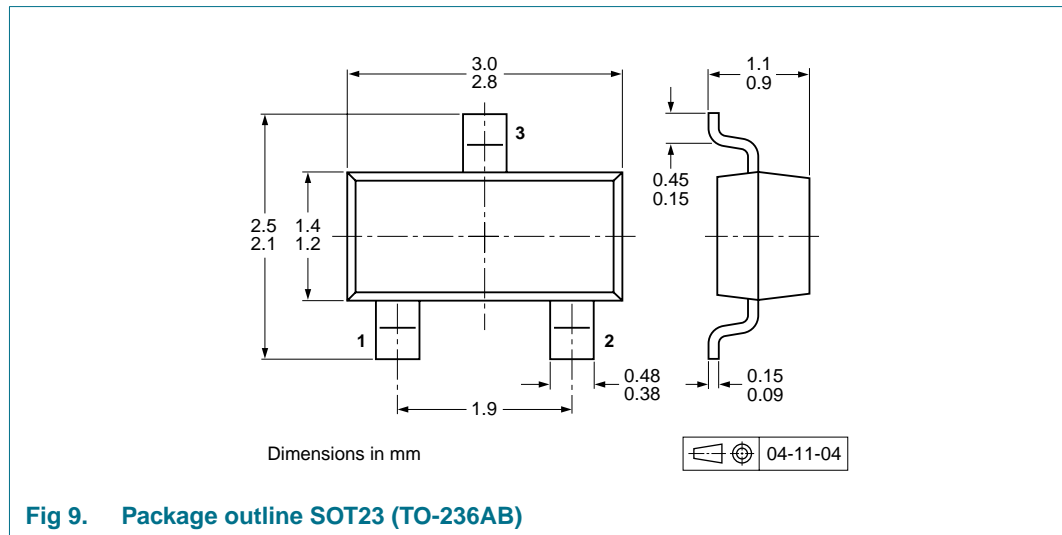
1. Place the NUP1301 as close to the input terminal or connector as possible.
2. The path length between the NUP1301 and the protected line should be minimized.
3. Keep parallel signal paths to a minimum.
4. Avoid running protected conductors in parallel with unprotected conductors.
5. Minimize all Printed-Circuit Board (PCB) conductive loops including power and ground loops.
6. Minimize the length of the transient return path to ground.
7. Avoid using shared transient return paths to a common ground point.
8. Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

9. Test information

9.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

10. Package outline



11. Packing information

Table 10. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

| Type number | Package | Description | Packing quantity | |
|-------------|---------|--------------------------------|------------------|-------|
| | | | 3000 | 10000 |
| NUP1301 | SOT23 | 4 mm pitch, 8 mm tape and reel | -215 | -235 |

[1] For further information and the availability of packing methods, see [Section 15](#).

12. Soldering

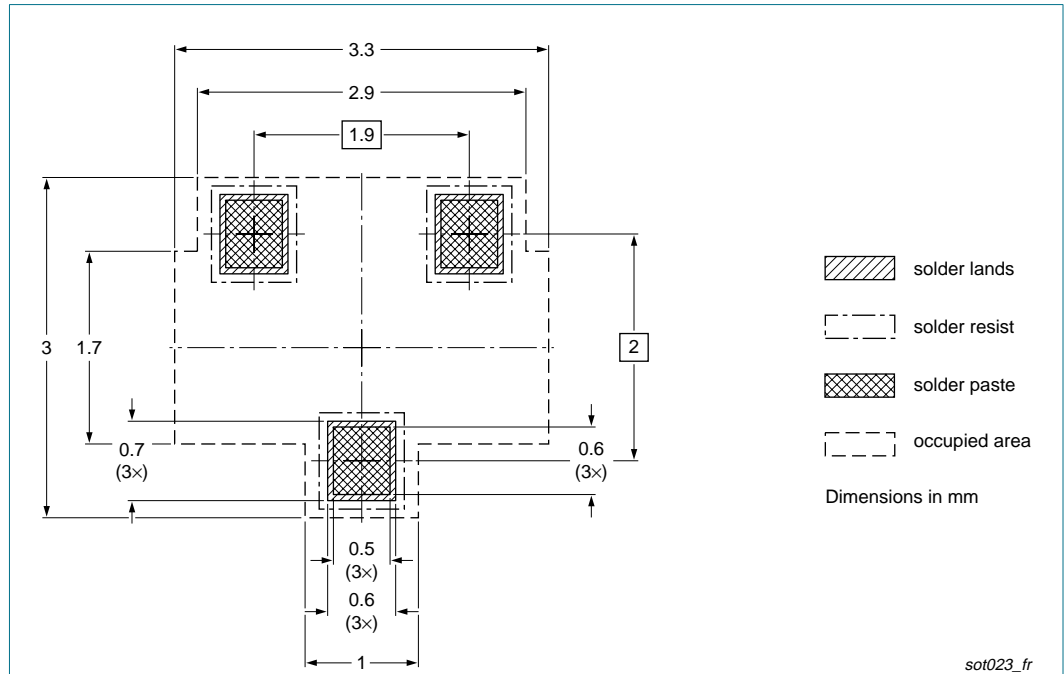


Fig 10. Reflow soldering footprint SOT23 (TO-236AB)

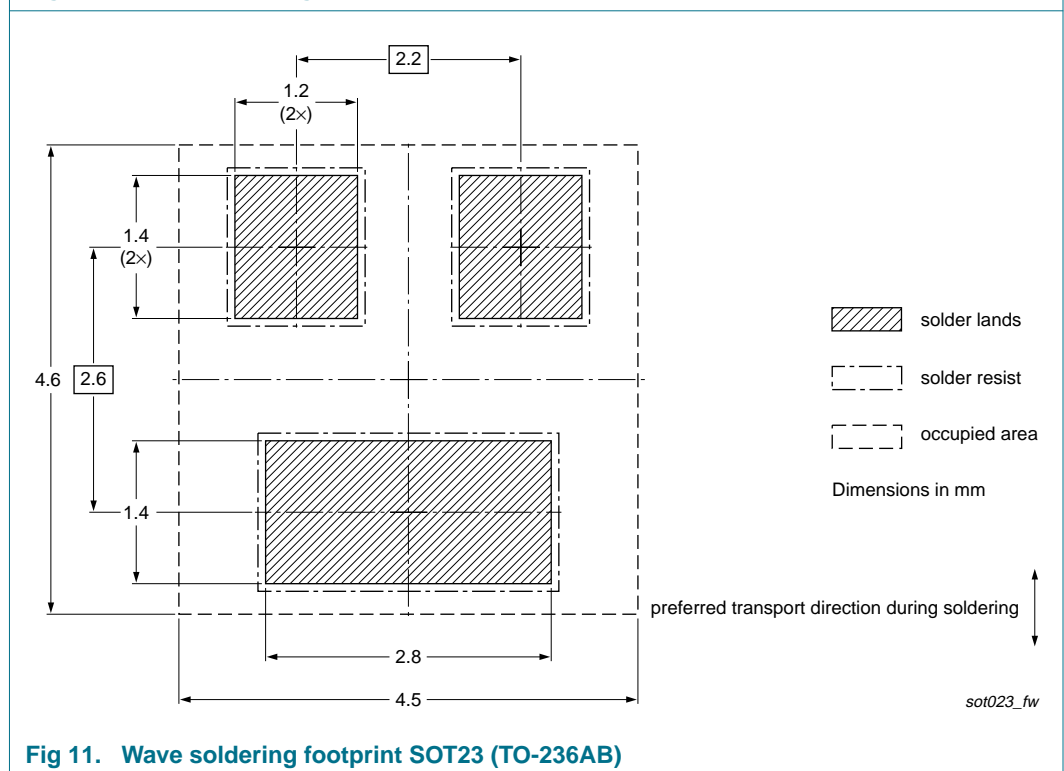


Fig 11. Wave soldering footprint SOT23 (TO-236AB)

13. Revision history

Table 11. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|-------------|--------------|--------------------|---------------|------------|
| NUP1301_1 | 20090511 | Product data sheet | - | - |

14. Legal information

14.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
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| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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16. Contents

| | | |
|-----------|--|-----------|
| 1 | Product profile | 1 |
| 1.1 | General description | 1 |
| 1.2 | Features | 1 |
| 1.3 | Applications | 1 |
| 1.4 | Quick reference data | 1 |
| 2 | Pinning information | 2 |
| 3 | Ordering information | 2 |
| 4 | Marking | 2 |
| 5 | Limiting values | 2 |
| 6 | Thermal characteristics | 4 |
| 7 | Characteristics | 5 |
| 8 | Application information | 8 |
| 9 | Test information | 8 |
| 9.1 | Quality information | 8 |
| 10 | Package outline | 9 |
| 11 | Packing information | 9 |
| 12 | Soldering | 10 |
| 13 | Revision history | 11 |
| 14 | Legal information | 12 |
| 14.1 | Data sheet status | 12 |
| 14.2 | Definitions | 12 |
| 14.3 | Disclaimers | 12 |
| 14.4 | Trademarks | 12 |
| 15 | Contact information | 12 |
| 16 | Contents | 13 |